

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Joseph M. Milewski and : Art Unit:  
Charles G. Woychik : Examiner:  
Serial No.: To Be Assigned :  
Filed: Herewith :  
For: LOW TEMPERATURE SOLDER :  
CHIP ATTACH STRUCTURE :

## DIVISIONAL APPLICATION OF:

Applicants: Joseph Milewski and : Art Unit: 1725  
Charles G. Woychik : Examiner: K. Stoner  
Serial No.: 08/815,656 :  
Filed: March 13, 1997 :  
For: PROCESS TO PRODUCE A :  
HIGH TEMPERATURE :  
INTERCONNECTION :

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents  
Washington, D.C. 20231

S I R :

Before examining the application first identified above, please  
amend that application as follows.

IN THE TITLE:

Please delete the title in its entirety and substitute therefor:

LOW TEMPERATURE SOLDER CHIP ATTACH STRUCTURE.

10004421-110201